

IN THE SPECIFICATION

Please amend the paragraph at page 4, lines 19-24 as follows:

According to an aspect of the present invention, there is provided a semiconductor device comprising a semiconductor chip comprising a magnetic element, an enclosure which seals the ~~magnetic~~ semiconductor chip and has a base material and a cap material joined together via a sealing material, and substantially spherical magnetic substance particles which are interspersed in ~~the enclosure~~ the base material and the cap material.

Please amend the paragraph at page 4, line 25 through page 5, line 6 as follows:

According to an aspect of the present invention, there is provided a semiconductor device comprising, a semiconductor chip comprising a magnetic element, an enclosure which seals the ~~magnetic~~ semiconductor chip and which has a base material and a cap material joined together via a sealing material, a magnetic film provided on a chip side surface of the base material and on an inner surface of the cap material so as to surround the semiconductor chip.

According to an aspect of the present invention, there is provided a semiconductor device comprising a semiconductor chip comprising a magnetic element, an enclosure which seals the semiconductor chip and substantially spherical magnetic substance particles which are interspersed in the enclosure, the particles preventing magnetic shape anisotropy.